



K-8958

1 MIL ESD POLYIMIDE FILM TAPE

APPLICATIONS

Designed to shield electromagnetic waves and static-charge in masking of the gold fingers on printed circuit boards during the wave solder applications that require reduced electrostatic discharge upon tape removal.. Ideal for sealing antistatic bags when packaging static sensitive components.

FEATURES/BENEFITS

- Excellent electrostatic discharge properties during roll unwind and surface removal.
- The high temperature polyimide film/silicone adhesive combination absorbs heat without shrinking or losing its construction integrity.
- Thin and conformable, with outstanding puncture, tear and abrasion resistance at elevated temperatures.
- Also available on a film release liner and in custom die-cut form for spot masking.

TECHNICAL DATA

Backing	:	1 mil Polyimide Film
Adhesive	:	Silicone (Antistatic Polymer)
Color	:	Amber
Tape Thickness	:	2.80 mils (0.056mm)
Elongation	:	55%
Adhesion to Steel	:	25 oz per inch of width (2.80N/cm)
Tensile Strength	:	30 lbs per inch of width (44 N/cm)
Temperature Range	:	-100°F to 500°F (-73° to 260°C)
Static Charge	:	
Roll Unwind	:	<50 Volts
Application Removal	:	<50 Volts
Specifications	:	UL 510 Flame Retardant

Note: The above are typical values obtained from tests recommended by the PSTC, ASTM, or government agencies and should not be used in writing specifications. The product should be thoroughly evaluated by the user under actual conditions with intended substrates to determine if the product is suitable for the application.